

# Second Announcement and Call for Papers or Extended Abstracts



2018 INTERNATIONAL SEMINAR ON  
ADVANCED MATERIALS RESEARCH

## 2018 ISAMR

*Sponsored by*

China Materials Research Society

Beijing Institute of Technology

Donghua University

Science and Technology on Applied Physical

Chemical Laboratory



Shanghai, China  
August 2–5, 2018

## Welcome to 2018 ISAMR

Two years ago, 2016 International Seminar on Advanced Materials Research (2016 ISAMR) was successfully held at Kunming Wenhui Hotel in Kunming, Yunnan Province, China, October, 14-16, 2016. 330 people attended the seminar and 135 speeches were made by scholars from more than ten countries. During the seminar, there were plenary session, eight parallel sessions and two special sessions honoring Academician Prof. Yiu-Wing Mai and Academician Prof. Wei Huang.

2018 International Seminar on Advanced Materials Research (2018 ISAMR) will be held in Donghua University, Shanghai on August 2-5, 2018, China. The seminar is not only a continuation, but also an extension of 2016 ISAMR. This series seminars are scheduled to be held every two years in China with topics of stimulating discussions on the forefront research in material science and technology. There have been twelve sessions, that is Nano Photonic Materials session, Organic Semiconductor and application session, Functional Biomaterials session, Biomedical Materials session, Advanced Composite Materials session, Advanced Fiber and Functional Textile Materials session, Energy Materials session, Energetic Materials session, Environmental-friendly Materials session, 3D Printing Materials session, Materials under Dynamic and Extreme Loading Conditions session, High-entropy Alloys session.

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## Main Topics

Nano Photonic Materials; Organic Semiconductor and  
Application; Functional Biomaterials; Biomedical  
Materials; Advanced Composite Materials; Advanced  
Fiber and Functional Textile Materials; Energy Materials;  
Energetic Materials; Environmental-friendly Materials; 3D  
Printing; Materials under Dynamic and Extreme Loading  
Conditions; High-entropy Alloys.

## Conference Language

The conference language is English, which will be used for all  
presentations and printed materials.

## Submission of Papers and Extended Abstracts

The seminar accept papers and extended abstracts, which  
must be submitted by the website <http://ISAMR.bit.edu.cn>  
NO LATER THAN May 10, 2018. The instructions for extended  
abstracts and papers can be found on the website.  
The author is also welcome to state his preference for oral or  
poster session, though both forms of delivery will be  
included in the Proceedings of 2018 ISAMR.

## Important Dates

May 10, 2018  
Final date for submission of extended abstracts  
May 20, 2018  
Authors notified of extended abstracts acceptance  
June 20, 2018  
Final Announcement with the list of extended abstracts  
August 2, 2018  
Registration  
August 3-5, 2018  
2018 ISAMR

## Registration Fee

The registration fee is US\$500, including one copy of the  
proceedings of the seminar, banquet, meals, coffee breaks.  
The fee for student is US\$300, including the proceedings of  
the seminar, meals, coffee breaks, and for companion is  
US\$300, including banquet, meals and shopping guide.  
Special functions require additional fees. The registration fee  
will be reduced to US\$400 and US\$250 respectively, if paid  
before July 10.

## Hotel

Songjiang New Century Grand Hotel Shanghai

## Secretariat

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